



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20220511003.0

**Datasheet for CDx4HC373, SNx4HC241, SNx4HC541, SNx4HC574 and SNx4HC377
Information Only**

Date: May 19, 2022
To: PREMIER FARNELL PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN team (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

**Information Only
Attachments**

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74HC541DWR	null
SN74HC574DW	null

Technical details of this Product Change follow on the next page(s).

Notification Number:	20220511003.0	Notification Date:	May 19, 2022
Title:	Datasheet for CDx4HC373, SNx4HC241, SNx4HC541, SNx4HC574, and SNx4HC377		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being updated as summarized below.
The following change history provides further details.



TEXAS
INSTRUMENTS

CD54HC373, CD74HC373

SCLS452C – FEBRUARY 2001 – REVISED MAY 2022

Changes from Revision B (January 2022) to Revision C (May 2022)

Page

- Junction-to-ambient thermal resistance values increased. DW was 58 is now 109.1, N was 69 is now 84.6.... 4



TEXAS
INSTRUMENTS

SN54HC241, SN74HC241

SCLS300E – JANUARY 1996 – REVISED MAY 2022

Changes from Revision D (January 2022) to Revision E (May 2022)

Page

- Junction-to-ambient thermal resistance values increased. DW was 58 is now 109.1, N was 69 is now 84.6, NS was 60 is now 113.4, PW was 83 is now 131.8..... 4



TEXAS
INSTRUMENTS

SN54HC541, SN74HC541

SCLS305E – JANUARY 1996 – REVISED MAY 2022

Changes from Revision D (September 2016) to Revision E (May 2022)

Page

- Updated ESD ratings table to include modern TI terminology..... 4
- Junction-to-ambient thermal resistance values increased. DB was 90.2 is now 122.7, DW was 77.5 is now 109.1, N was 45.2 is now 84.6, NS was 72.8 is now 113.4, PW was 98.3 is now 131.8..... 5



TEXAS
INSTRUMENTS

SN54HC574, SN74HC574

SCLS148H – DECEMBER 1982 – REVISED MAY 2022

Changes from Revision G (December 2021) to Revision H (May 2022)

Page

- Junction-to-ambient thermal resistance values increased. DW was 58 is now 109.1, DB was 70 is now 122.7, N was 69 is now 84.6, NS was 60 is now 113.4, PW was 83 is now 131.8..... 4



TEXAS
INSTRUMENTS

SN54HC377, SN74HC377

SCLS307D – JANUARY 1996 – REVISED MAY 2022

Changes from Revision C (January 2022) to Revision D (May 2022)

Page

- Junction-to-ambient thermal resistance values increased. DW was 58 is now 109.1, N was 69 is now 84.6, NS was 60 is now 113.4..... 4

The datasheet number will be changing.

Device Family	Change From:	Change To:
CDx4HC373	SCLS452B	SCLS452C
SNx4HC241	SCLS300D	SCLS300E
SNx4HC541	SCLS305D	SCLS305E
SNx4HC574	SCLS148G	SCLS148H
SNx4HC377	SCLS307C	SCLS307D

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/CD54HC373>

<http://www.ti.com/product/SN54HC241>

<http://www.ti.com/product/SN54HC541>

<http://www.ti.com/product/SNx4HC574>

<http://www.ti.com/product/SNx4HC377>

Error! Bookmark not defined.

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this notification:

None.

Product Affected:

CD74HC373E	SN74HC241PWG4	SN74HC541DWR	SN74HC574DW
CD74HC373EE4	SN74HC241PWR	SN74HC541N	SN74HC574DWG4
CD74HC373M	SN74HC241PWRE4	SN74HC541NE4	SN74HC574DWR
CD74HC373M96	SN74HC377DW	SN74HC541NS	SN74HC574N
CD74HC373ME4	SN74HC377DWR	SN74HC541NSR	SN74HC574NE4
SN74HC241DW	SN74HC377N	SN74HC541PW	SN74HC574NS
SN74HC241DWE4	SN74HC377NE4	SN74HC541PWG4	SN74HC574NSR
SN74HC241DWR	SN74HC377NSR	SN74HC541PWR	SN74HC574PW
SN74HC241DWRG4	SN74HC541DBR	SN74HC541PWT	SN74HC574PWR
SN74HC241N	SN74HC541DW	SN74HC574APWR	SN74HC574PWRE4
SN74HC241NSR	SN74HC541DWE4	SN74HC574DBR	SN74HC574PWRG4
SN74HC241PW	SN74HC541DWG4	SN74HC574DBRG4	SN74HC574PWT

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail
WW PCN Team	PCN_ww_admin_team@list.ti.com

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